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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	Z8
Core Size	8-Bit
Speed	12MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	14
Program Memory Size	2KB (2K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	125 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z86e0812hsg1866

GENERAL DESCRIPTION (Continued)

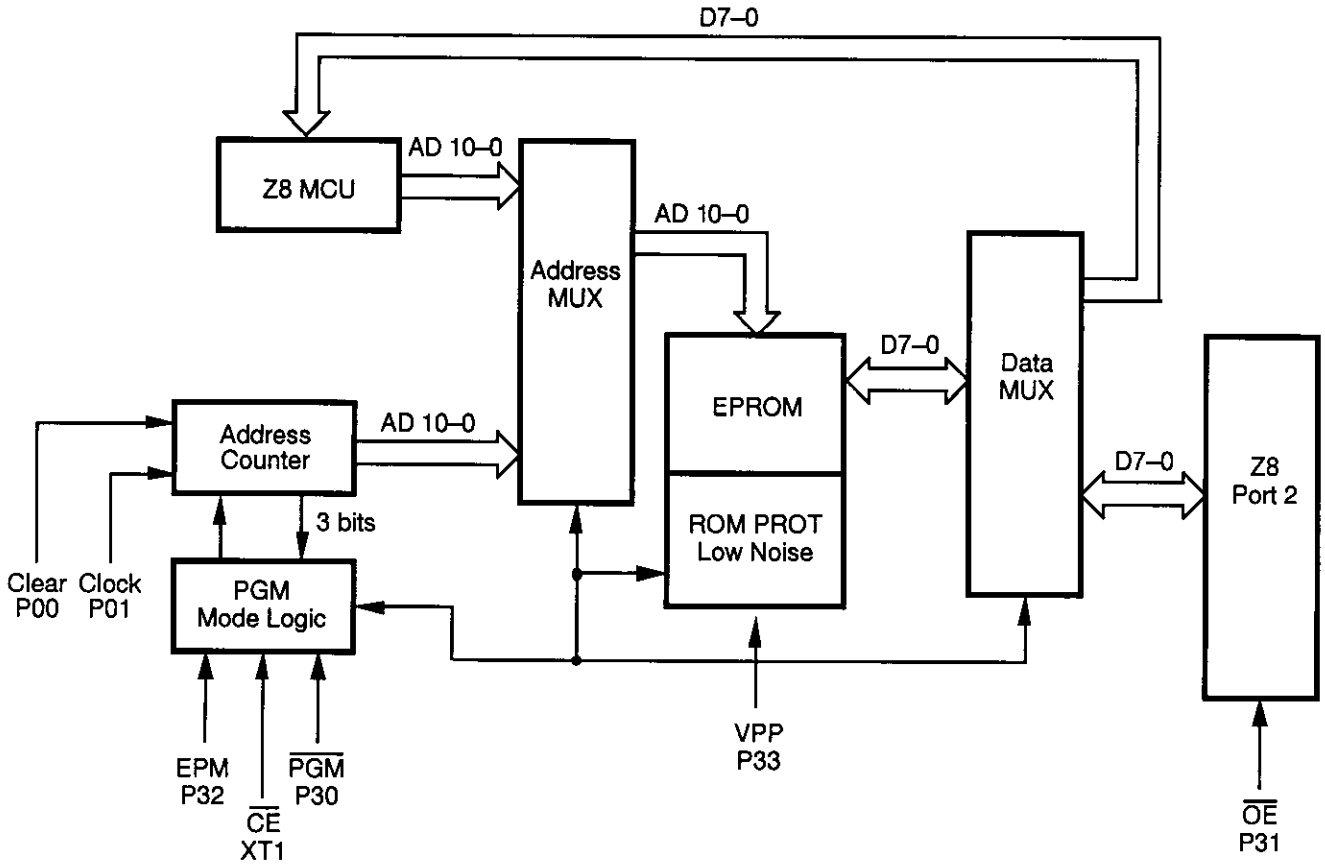


Figure 2. EPROM Programming Mode Block Diagram

ABSOLUTE MAXIMUM RATINGS

Stresses greater than those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at any condition above those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for an extended period may affect device reliability. Total power dissipation should not exceed 462 mW for the package. Power dissipation is calculated as follows:

Total Power Dissipation = V_{DD} x [I_{DD}–(sum of I_{OH})]
+ sum of [(V_{DD}–V_{OH}) x I_{OH}]
+ sum of (V_{OL} x I_{OL})

Parameter	Min	Max	Units	Note
Ambient Temperature under Bias	–40	+105	C	
Storage Temperature	–65	+150	C	
Voltage on any Pin with Respect to V_{SS}	–0.7	+12	V	1
Voltage on V_{DD} Pin with Respect to V_{SS}	–0.3	+7	V	
Voltage on Pins 7, 8, 9, 10 with Respect to V_{SS}	–0.6	V_{DD}+1	V	2
Total Power Dissipation		1.65	W	
Maximum Allowable Current out of V_{SS}		300	mA	
Maximum Allowable Current into V_{DD}		220	mA	
Maximum Allowable Current into an Input Pin	–600	+600	µA	3
Maximum Allowable Current into an Open-Drain Pin	–600	+600	µA	4
Maximum Allowable Output Current Sinked by Any I/O Pin		25	mA	
Maximum Allowable Output Current Sourced by Any I/O Pin		25	mA	
Total Maximum Output Current Sinked by a Port		60	mA	
Total Maximum Output Current Sourced by a Port		45	mA	

Notes:

1. This applies to all pins except where otherwise noted. Maximum current into pin must be ± 600 µA.
2. There is no input protection diode from pin to V_{DD} (not applicable to EPROM Mode).
3. This excludes Pin 6 and Pin 7.
4. Device pin is not at an output Low state.

Sym	Parameter	V_{CC} [4]	T_A = 0°C to +70°C Min	Max	Typical @ 25°C	Units	Conditions	Notes
I_{CC}	Supply Current	4.5V		11.0	6.8	mA	All Output and I/O Pins Floating @ 2 MHz	5,7
		5.5V		11.0	6.8	mA	All Output and I/O Pins Floating @ 2 MHz	5,7
		4.5V		15.0	8.2	mA	All Output and I/O Pins Floating @ 8 MHz	5,7
		5.5V		15.0	8.2	mA	All Output and I/O Pins Floating @ 8 MHz	5,7
		4.5V		20.0	12.0	mA	All Output and I/O Pins Floating @ 12 MHz	5,7
		5.5V		20.0	12.0	mA	All Output and I/O Pins Floating @ 12 MHz	5,7
I_{CC1}	Standby Current	4.5V		4.0	2.5	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 2 MHz	5,7
		5.5V		4.0	2.5	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 2 MHz	5,7
		4.5V		5.0	3.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 8 MHz	5,7
		5.5V		5.0	3.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 8 MHz	5,7
		4.5V		7.0	4.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 12 MHz	5,7
		5.5V		7.0	4.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 12 MHz	5,7
I_{CC}	Supply Current (Low Noise Mode)	4.5V		11.0	6.8	mA	All Output and I/O Pins Floating @ 1 MHz	7
		5.5V		11.0	6.8	mA	All Output and I/O Pins Floating @ 1 MHz	7
		4.5V		13.0	7.5	mA	All Output and I/O Pins Floating @ 2 MHz	7
		5.5V		13.0	7.5	mA	All Output and I/O Pins Floating @ 2 MHz	7
		4.5V		15.0	8.2	mA	All Output and I/O Pins Floating @ 4 MHz	7
		5.5V		15.0	8.2	mA	All Output and I/O Pins Floating @ 4 MHz	7

DC ELECTRICAL CHARACTERISTICS

Extended Temperature

Sym	Parameter	V_{CC} [4]	T_A = –40°C to +105°C Min	Max	Typical @ 25°C	Units	Conditions	Notes
V_{INMAX}	Max Input Voltage	4.5V		12.0		V	I_{IN} < 250 µA	1
		5.5V		12.0		V	I_{IN} < 250 µA	1
V_{CH}	Clock Input High Voltage	4.5V	0.8 V_{CC}	V_{CC}+0.3	2.8	V	Driven by External Clock Generator	
		5.5V	0.8 V_{CC}	V_{CC}+0.3	2.8	V	Driven by External Clock Generator	
V_{CL}	Clock Input Low Voltage	4.5V	V_{SS}–0.3	0.2 V_{CC}	1.7	V	Driven by External Clock Generator	
		5.5V	V_{SS}–0.3	0.2 V_{CC}	1.7	V	Driven by External Clock Generator	
V_{IH}	Input High Voltage	4.5V	0.7 V_{CC}	V_{CC}+0.3	2.8	V		
		5.5V	0.7 V_{CC}	V_{CC}+0.3	2.8	V		
V_{IL}	Input Low Voltage	4.5V	V_{SS}–0.3	0.2 V_{CC}	1.5	V		
		5.5V	V_{SS}–0.3	0.2 V_{CC}	1.5	V		
V_{OH}	Output High Voltage	4.5V	V_{CC}–0.4		4.8	V	I_{OH} = –2.0 mA	5
		5.5V	V_{CC}–0.4		4.8	V	I_{OH} = –2.0 mA	5
		4.5V	V_{CC}–0.4			V	Low Noise @ I_{OH} = –0.5 mA	
		5.5V	V_{CC}–0.4			V	Low Noise @ I_{OH} = –0.5 mA	
V_{OL1}	Output Low Voltage	4.5V		0.4	0.1	V	I_{OL} = +4.0 mA	5
		5.5V		0.4	0.1	V	I_{OL} = +4.0 mA	5
		4.5V		0.4	0.1	V	Low Noise @ I_{OL} = 1.0 mA	
		5.5V		0.4	0.1	V	Low Noise @ I_{OL} = 1.0 mA	
V_{OL2}	Output Low Voltage	4.5V		1.0	0.3	V	I_{OL} = +12 mA,	5
		5.5V		1.0	0.3	V	I_{OL} = +12 mA,	5
V_{OFFSET}	Comparator Input Offset Voltage	4.5V		25.0	10.0	mV		
		5.5V		25.0	10.0	mV		
V_{LV}	V_{CC} Low Voltage Auto Reset		1.8	3.8	2.8	V	@ 6 MHz Max. Int. CLK Freq.	3
I_{IL}	Input Leakage (Input Bias Current of Comparator)	4.5V		–1.0	1.0	µA	V_{IN} = 0V, V_{CC}	
		5.5V		–1.0	1.0	µA	V_{IN} = 0V, V_{CC}	
I_{OL}	Output Leakage	4.5V		–1.0	1.0	µA	V_{IN} = 0V, V_{CC}	
		5.5V		–1.0	1.0	µA	V_{IN} = 0V, V_{CC}	
V_{ICR}	Comparator Input Common Mode Voltage Range		0	V_{CC} –1.5		V		

Sym	Parameter	V_{CC} [4]	T_A = –40°C to +105°C Min	Max	Typical @ 25°C	Units	Conditions	Notes
I_{CC1}	Standby Current (Low Noise Mode)	4.5V		4.0	2.5	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 1 MHz	7
		5.5V		4.0	2.5	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 1 MHz	7
		4.5V		4.5	2.8	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 2 MHz	7
		5.5V		4.5	2.8	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 2 MHz	7
		4.5V		5.0	3.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 4 MHz	7
		5.5V		5.0	3.0	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 4 MHz	7
I_{CC2}	Standby Current	4.5V		20	1.0	µA	STOP Mode V_{IN} = 0V, V_{CC} WDT is not Running	7,8
		5.5V		20	1.0	µA	STOP Mode V_{IN} = 0V, V_{CC} WDT is not Running	7,8
I_{ALL}	Auto Latch Low Current	4.5V		40	16	µA	$0V < V_{IN} < V_{CC}$	
		5.5V		40	16	µA	$0V < V_{IN} < V_{CC}$	
I_{ALH}	Auto Latch High Current	4.5V		–20.0	–8.0	µA	$0V < V_{IN} < V_{CC}$	
		5.5V		–20.0	–8.0	µA	$0V < V_{IN} < V_{CC}$	

Notes:

1. Port 2 and Port 0 only
2. V_{SS} = 0V = GND
3. The device operates down to V_{LV} of the specified frequency for V_{LV}. The minimum operational V_{CC} is determined on the value of the voltage V_{LV} at the ambient temperature. The V_{LV} increases as the temperature decreases.
4. V_{CC} = 4.5V to 5.5V, typical values measured at V_{CC} = 5.0V
5. Standard Mode (not Low EMI Mode)
6. Z86E08 only
7. All outputs unloaded and all inputs are at V_{CC} or V_{SS} level.
8. If analog comparator is selected, then the comparator inputs must be at V_{CC} level.

AC ELECTRICAL CHARACTERISTICS

Timing Table (Standard Mode for SCLK/TCLK = XTAL/2)
Standard Temperature

15				T_A= 0 °C to +70 °C						
				8 MHz		12 MHz				
No	Symbol	Parameter	V_{CC}	Min	Max	Min	Max	Units	Notes
1	TpC	Input Clock Period	4.5V	125	DC	83	DC	ns	1
			5.5V	125	DC	83	DC	ns	1
2	TrC,TfC	Clock Input Rise and Fall Times	4.5V		25		15	ns	1
			5.5V		25		15	ns	1
3	TwC	Input Clock Width	4.5V	62		41		ns	1
			5.5V	62		41		ns	1
4	TwTinL	Timer Input Low Width	4.5V	100		100		ns	1
			5.5V	70		70		ns	1
5	TwTinH	Timer Input High Width	4.5V	5TpC		5TpC			1
			5.5V	5TpC		5TpC			1
6	TpTin	Timer Input Period	4.5V		8TpC	8TpC			1
			5.5V		8TpC	8TpC			1
7	TrTin, TtTin	Timer Input Rise and Fall Time	4.5V		100		100	ns	1
			5.5V		100		100	ns	1
8	TwIL	Int. Request Input Low Time	4.5V	70		70		ns	1,2
			5.5V	70		70		ns	1,2
9	TwIH	Int. Request Input High Time	4.5V		5TpC	5TpC			1,2
			5.5V		5TpC	5TpC			1,2
10	Twdt	Watch-Dog Timer Delay Time for Timeout	4.5V	12		12		ms	1
			5.5V	12		12		ms	1
11	Tpor	Power-On Reset Time	4.5V	20	80	20	80	ms	1
			5.5V	20	80	20	80	ms	1

Notes:

1. Timing Reference uses 0.7 V_{CC} for a logic 1 and 0.2 V_{CC} for a logic 0.
2. Interrupt request through Port 3 (P33–P31).

PIN FUNCTIONS (Continued)

XTAL1, XTAL2 *Crystal In, Crystal Out* (time-based input and output, respectively). These pins connect a parallel-resonant crystal, LC, or an external single-phase clock (8 MHz or 12 MHz max) to the on-chip clock oscillator and buffer.

Port 0, P02–P00. Port 0 is a 3-bit bidirectional, Schmitt-triggered CMOS-compatible I/O port. These three I/O lines can be globally configured under software control to be inputs or outputs (Figure 7).

Auto Latch. The Auto Latch puts valid CMOS levels on all CMOS inputs (except P33, P32, P31) that are not externally driven. A valid CMOS level, rather than a floating node, reduces excessive supply current flow in the input buffer. On Power-up and Reset, the Auto Latch will set the ports to an undetermined state of 0 or 1. Default condition is Auto Latches enabled.

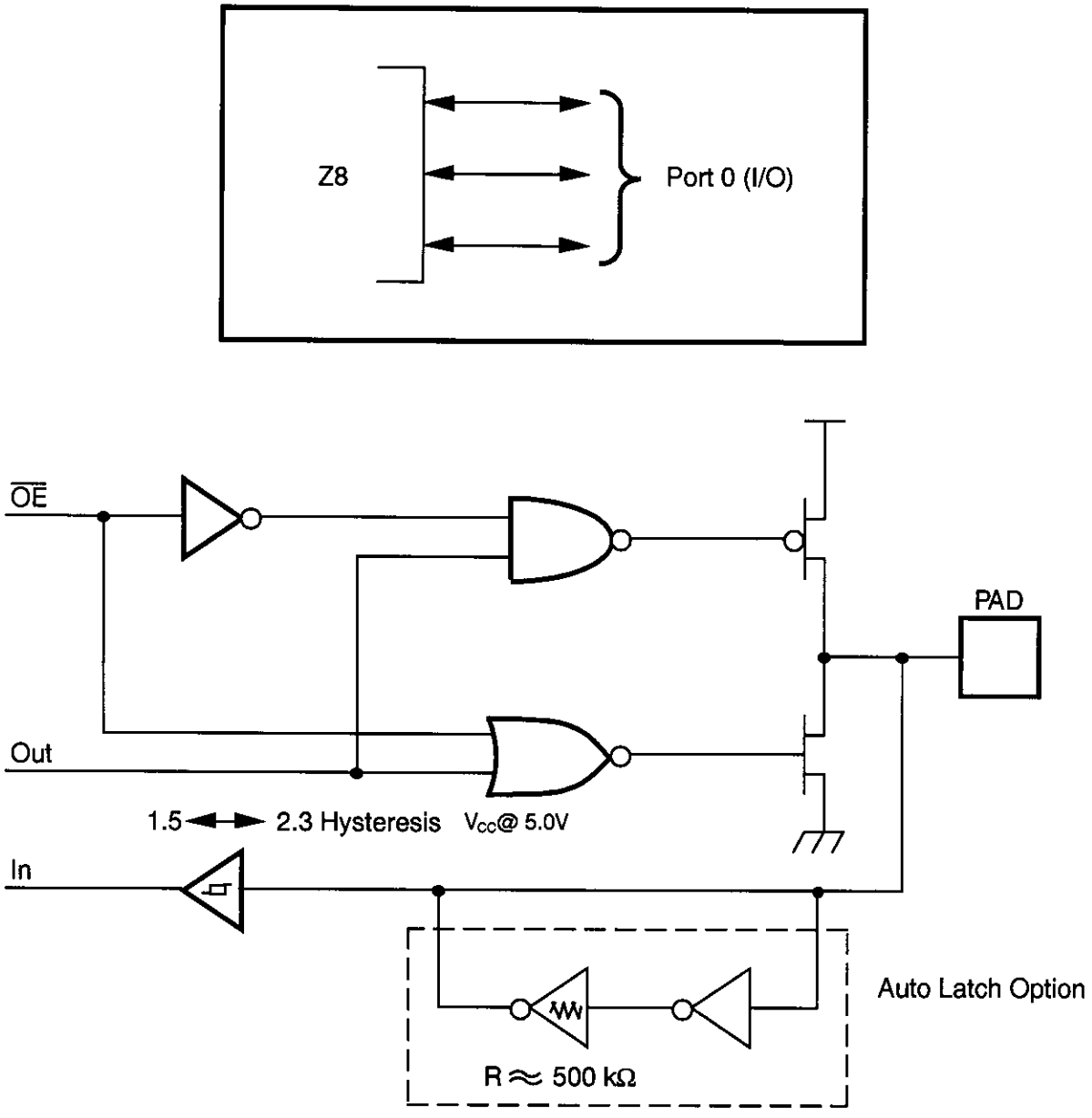


Figure 7. Port 0 Configuration

Port 2, P27–P20. Port 2 is an 8-bit, bit programmable, bidirectional, Schmitt-triggered CMOS-compatible I/O port. These eight I/O lines can be configured under software control to be inputs or outputs, independently. Bits programmed as outputs can be globally programmed as either push-pull or open-drain (Figure 8).

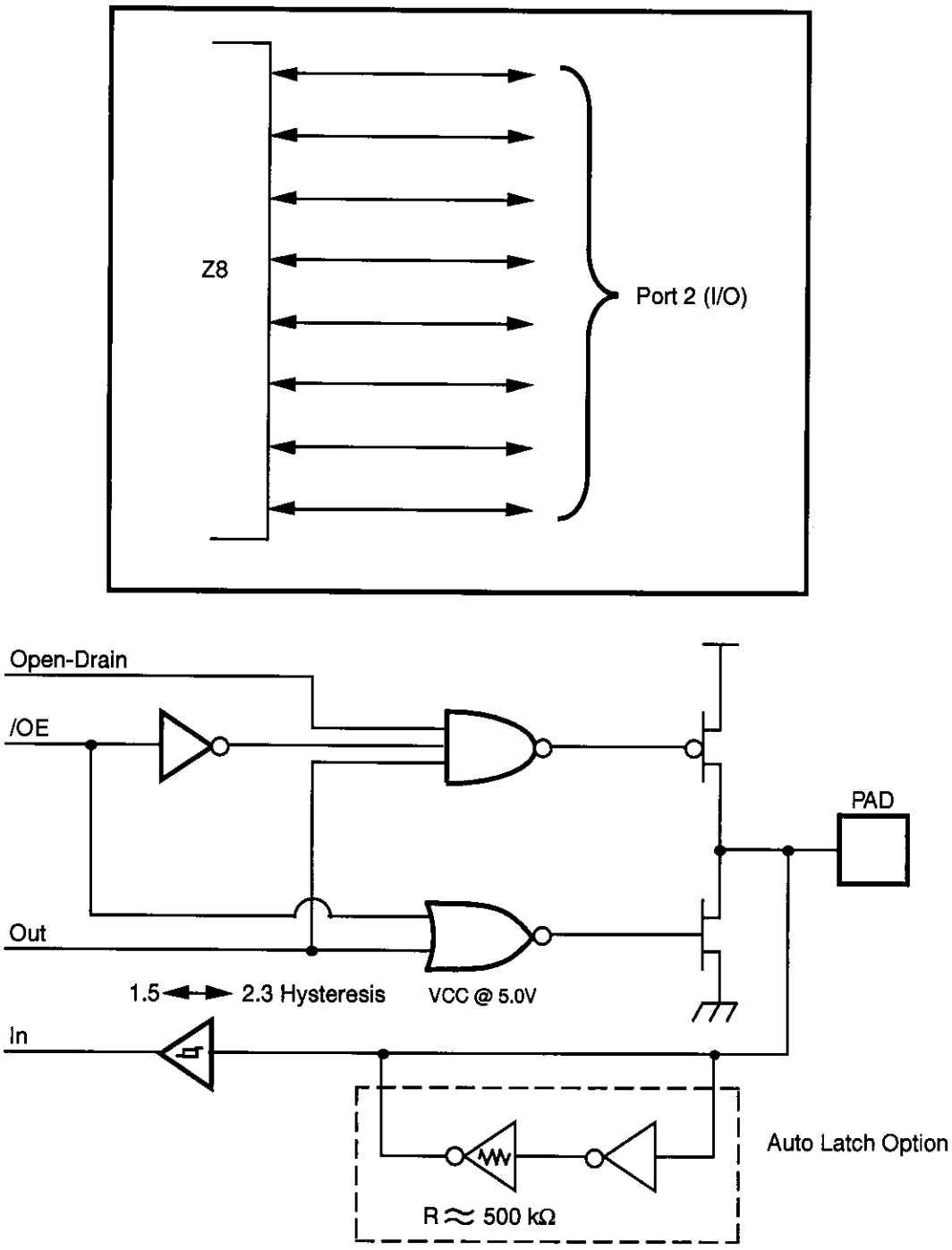


Figure 8. Port 2 Configuration

Program Memory. The Z86E04/E08 addresses up to 1K/2KB of Internal Program Memory (Figure 11). The first 12 bytes of program memory are reserved for the interrupt vectors. These locations contain six 16-bit vectors that correspond to the six available interrupts. Bytes 0–1024/2048 are on-chip one-time programmable ROM.

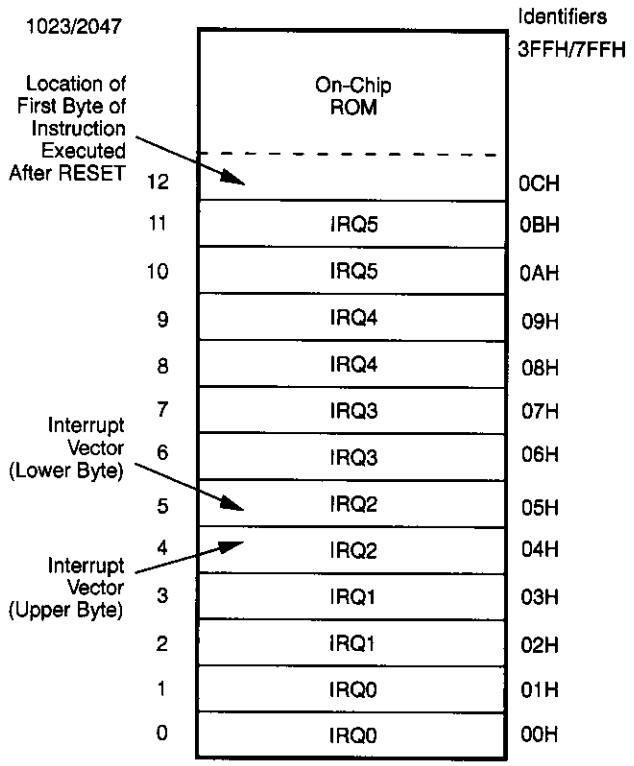


Figure 11. Program Memory Map

Register File. The Register File consists of three I/O port registers, 124 general-purpose registers, and 14 control and status registers R0–R3, R4–R127 and R241–R255, respectively (Figure 12). General-purpose registers occupy the 04H to 7FH address space. I/O ports are mapped as per the existing CMOS Z8.

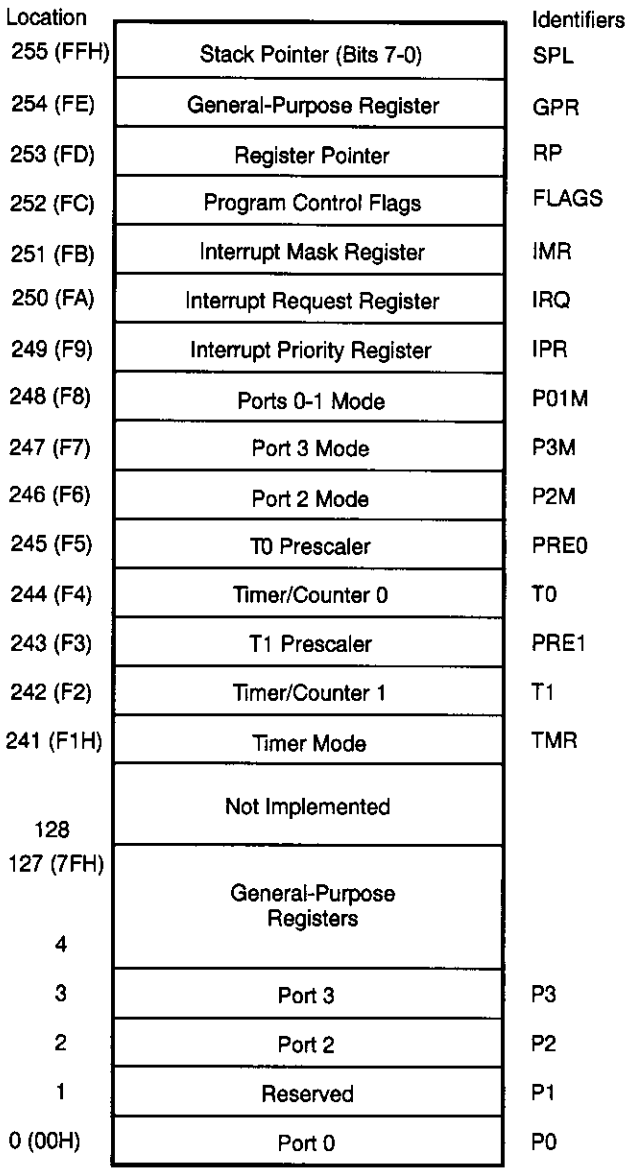


Figure 12. Register File

FUNCTIONAL DESCRIPTION (Continued)

The Z8 instructions can access registers directly or indirectly through an 8-bit address field. This allows short 4-bit register addressing using the Register Pointer.

In the 4-bit mode, the register file is divided into eight working register groups, each occupying 16 continuous locations. The Register Pointer (Figure 13) addresses the starting location of the active working-register group.

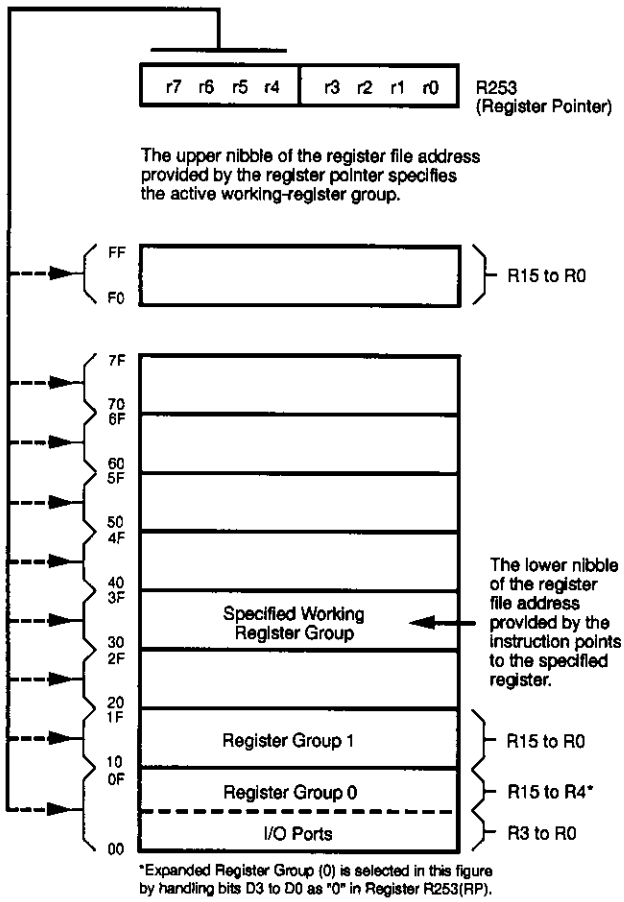


Figure 13. Register Pointer

Stack Pointer. The Z8 has an 8-bit Stack Pointer (R255) used for the internal stack that resides within the 124 general-purpose registers.

General-Purpose Registers (GPR). These registers are undefined after the device is powered up. The registers keep their last value after any reset, as long as the reset occurs in the V_{CC} voltage-specified operating range. **Note:** Register R254 has been designated as a general-purpose register and is set to 00 Hex after any reset or Stop-Mode Recovery.

Counter/Timer. There are two 8-bit programmable counter/timers (T0 and T1), each driven by its own 6-bit programmable prescaler. The T1 prescaler is driven by internal or external clock sources; however, the T0 can be driven by the internal clock source only (Figure 14).

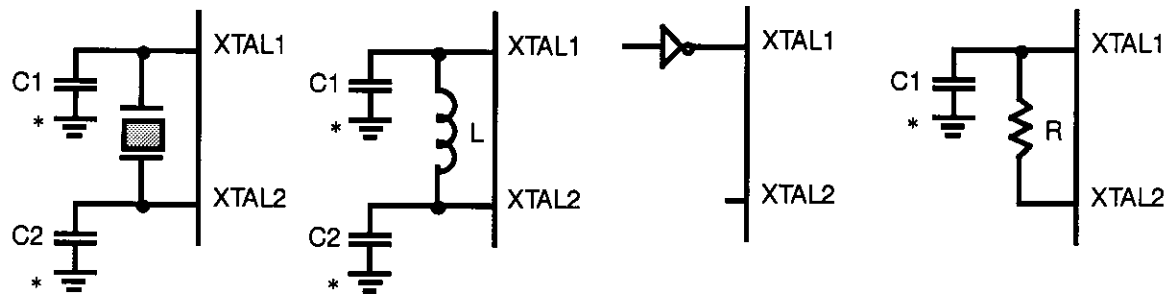
The 6-bit prescalers divide the input frequency of the clock source by any integer number from 1 to 64. Each prescaler drives its counter, which decrements the value (1 to 256) that has been loaded into the counter. When both counter and prescaler reach the end of count, a timer interrupt request IRQ4 (T0) or IRQ5 (T1) is generated.

The counter can be programmed to start, stop, restart to continue, or restart from the initial value. The counters are also programmed to stop upon reaching zero (Single-Pass Mode) or to automatically reload the initial value and continue counting (Modulo-N Continuous Mode).

The counters, but not the prescalers, are read at any time without disturbing their value or count mode. The clock source for T1 is user-definable and is either the internal microprocessor clock divided by four, or an external signal input through Port 3. The Timer Mode register configures the external timer input (P31) as an external clock, a trigger input that is retriggerable or non-retriggerable, or used as a gate input for the internal clock.

Clock. The Z8 on-chip oscillator has a high-gain, parallel-resonant amplifier for connection to a crystal, LC, RC, ceramic resonator, or any suitable external clock source (XTAL1 = INPUT, XTAL2 = OUTPUT). The crystal should be AT cut, up to 12 MHz max., with a series resistance (RS) of less than or equal to 100 Ohms.

The crystal should be connected across XTAL1 and XTAL2 using the vendors crystal recommended capacitors from each pin directly to device ground pin 14 (Figure 16). Note that the crystal capacitor loads should be connected to V_{SS}, Pin 14 to reduce Ground noise injection.



Ceramic Resonator or Crystal
C1, C2 = 47 pF TYP *
F = 8 MHz

LC

External Clock

RC
@ 5V Vcc (TYP)

C1 = 100 pF
R = 2K
F = 6 MHz

* Typical value including pin parasitics

Figure 16. Oscillator Configuration

FUNCTIONAL DESCRIPTION (Continued)

Table 5. Typical Frequency vs. RC Values
V_{CC} = 5.0V @ 25°C

	Load Capacitor							
	33 pFd		56 pFd		100 pFd		0.00 1µFd	
Resistor (R)	A(Hz)	B(Hz)	A(Hz)	B(Hz)	A(Hz)	B(Hz)	A(Hz)	B(Hz)
1.0M	33K	31K	20K	20K	12K	11K	1.4K	1.4K
560K	56K	52K	34K	32K	20K	19K	2.5K	2.4K
220K	144K	130K	84K	78K	48K	45K	6K	6K
100K	315K	270K	182K	164K	100K	95K	12K	12K
56K	552K	480K	330K	300K	185K	170K	23K	22K
20K	1.4M	1M	884K	740K	500K	450K	65K	61K
10K	2.6M	2M	1.6M	1.3M	980K	820K	130K	123K
5K	4.4M	3M	2.8M	2M	1.7K	1.3M	245K	225K
2K	8M	5M	6M	4M	3.8K	2.7M	600K	536K
1K	12M	7M	8.8M	6M	6.3K	4.2M	1.0M	950K

Notes:
A = STD Mode Frequency.
B = Low EMI Mode Frequency.

Table 6. Typical Frequency vs. RC Values
V_{CC} = 3.3V @ 25°C

	Load Capacitor							
Resistor (R)	33 pFd		56 pFd		100 pFd		0.00 1µFd	
	A(Hz)	B(Hz)	A(Hz)	B(Hz)	A(Hz)	B(Hz)	A(Hz)	B(Hz)
1.0M	18K	18K	12K	12K	7.4K	7.7K	1K	1K
560K	30K	30K	20K	20K	12K	12K	1.6K	1.6K
220K	70K	70K	47K	47K	30K	30K	4K	4K
100K	150K	148K	97K	96K	60K	60K	8K	8K
56K	268K	250K	176K	170K	100K	100K	15K	15K
20K	690M	600K	463K	416K	286K	266K	40K	40K
10K	1.2M	1M	860K	730K	540K	480K	80K	76K
5K	2M	1.7M	1.5M	1.2M	950K	820K	151K	138K
2K	4.6M	3M	3.3M	2.4M	2.2M	1.6M	360K	316K
1K	7M	4.6M	5M	3.6M	3.6K	2.6M	660K	565K

Notes:
A = STD Mode Frequency.
B = Low EMI Mode Frequency.

HALT Mode. This instruction turns off the internal CPU clock but not the crystal oscillation. The counter/timers and external interrupts IRQ0, IRQ1, IRQ2 and IRQ3 remain active. The device is recovered by interrupts, either externally or internally generated. An interrupt request must be executed (enabled) to exit HALT Mode. After the interrupt service routine, the program continues from the instruction after the HALT.

Note: On the C12 ICEBOX, the IRQ3 does not wake the device out of HALT Mode.

STOP Mode. This instruction turns off the internal clock and external crystal oscillation and reduces the standby current to 10 µA. The STOP Mode is released by a RESET through a Stop-Mode Recovery (pin P27). A Low input condition on P27 releases the STOP Mode. Program execution begins at location 000C(Hex). However, when P27 is used to release the STOP Mode, the I/O port Mode registers are not reconfigured to their default power-on conditions. This prevents any I/O, configured as output when the STOP instruction was executed, from glitching to an unknown state. To use the P27 release approach with STOP Mode, use the following instruction:

```
LD          P2M, #1XXX XXXXB
NOP
STOP
```

X = Dependent on user's application.

Note: A low level detected on P27 pin will take the device out of STOP Mode even if configured as an output.

In order to enter STOP or HALT Mode, it is necessary to first flush the instruction pipeline to avoid suspending execution in mid-instruction. To do this, the user executes a NOP (opcode=FFH) immediately before the appropriate SLEEP instruction, such as:

```
FF      NOP     ; clear the pipeline
6F      STOP    ; enter STOP Mode
            or
FF      NOP     ; clear the pipeline
7F      HALT    ; enter HALT Mode
```

Watch-Dog Timer (WDT). The Watch-Dog Timer is enabled by instruction WDT. When the WDT is enabled, it cannot be stopped by the instruction. With the WDT instruction, the WDT is refreshed when it is enabled within every 1 Twdt period; otherwise, the controller resets itself, The WDT instruction affects the flags accordingly; Z=1, S=0, V=0.

WDT = 5F (Hex)

Opcode WDT (5FH). The first time Opcode 5FH is executed, the WDT is enabled and subsequent execution clears the WDT counter. This must be done at least every T_{WDT}; otherwise, the WDT times out and generates a reset. The generated reset is the same as a power-on reset of T_{POR}, plus 18 XTAL clock cycles. The software enabled WDT does not run in STOP Mode.

Opcode WDH (4FH). When this instruction is executed it enables the WDT during HALT. If not, the WDT stops when entering HALT. This instruction does not clear the counters, it just makes it possible to have the WDT running during HALT Mode. A WDH instruction executed without executing WDT (5FH) has no effect.

Permanent WDT. Selecting the hardware enabled Permanent WDT option, will automatically enable the WDT upon exiting reset. The permanent WDT will always run in HALT Mode and STOP Mode, and it cannot be disabled.

Auto Reset Voltage (V_{LV}). The Z8 has an auto-reset built-in. The auto-reset circuit resets the Z8 when it detects the V_{CC} below V_{LV}.

Figure 17 shows the Auto Reset Voltage versus temperature. If the V_{CC} drops below the VCC operating voltage range, the Z8 will function down to the V_{LV} unless the internal clock frequency is higher than the specified maximum V_{LV} frequency.

FUNCTIONAL DESCRIPTION (Continued)

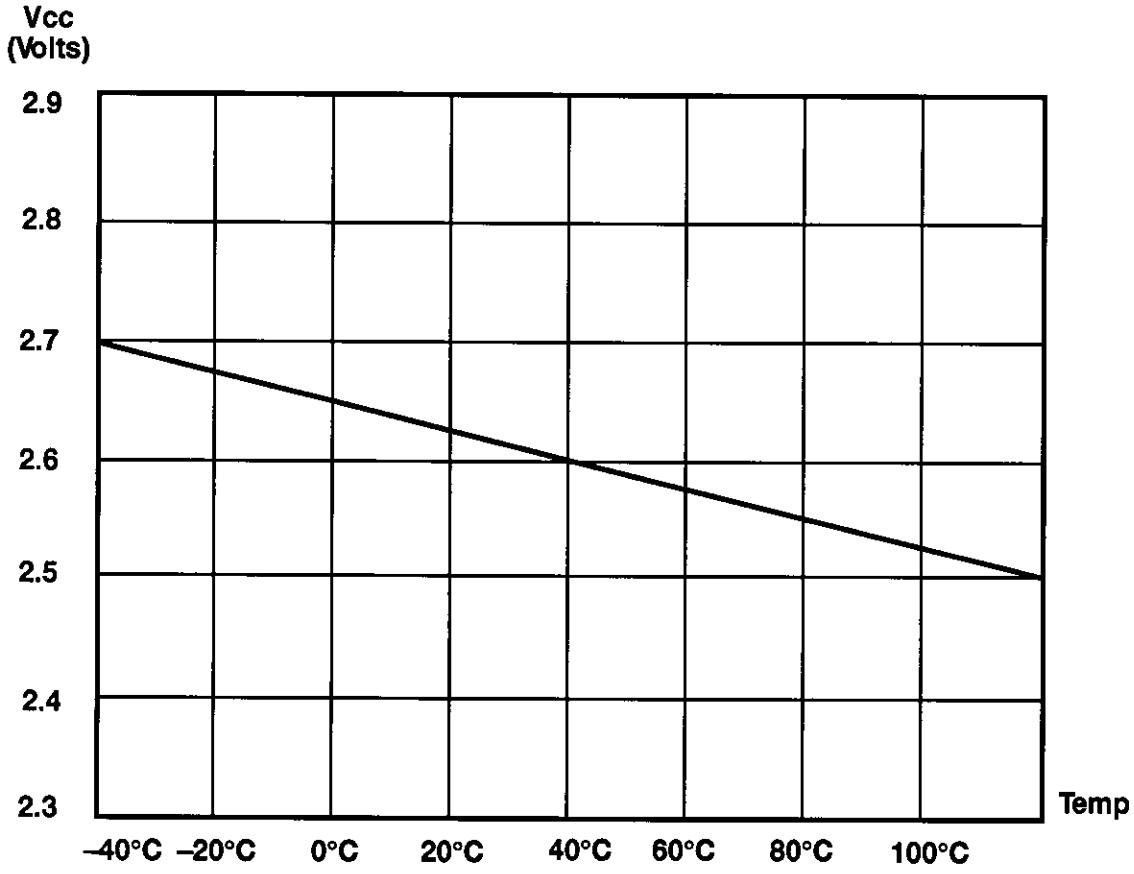


Figure 17. Typical Auto Reset Voltage (V_{LV}) vs. Temperature

Low EMI Emission

The Z8 can be programmed to operate in a low EMI Emission (Low Noise) Mode by means of an EPROM programmable bit option. Use of this feature results in:

- Less than 1 mA consumed during HALT Mode.
- All drivers slew rates reduced to 10 ns (typical).
- Internal SCLK/TCLK = XTAL operation limited to a maximum of 4 MHz–250 ns cycle time.
- Output drivers have resistances of 500 ohms (typical).
- Oscillator divide-by-two circuitry eliminated.

In addition to V_{DD} and GND (V_{SS}), the Z8 changes all its pin functions in the EPROM Mode. XTAL2 has no function, XTAL1 functions as $\overline{CE}$, P31 functions as $\overline{OE}$, P32 functions as EPM, P33 functions as V_{PP}, and P02 functions as $\overline{PGM}$.

ROM Protect. ROM Protect fully protects the Z8 ROM code from being read externally. When ROM Protect is selected, the instructions LDC and LDCI **are supported** (Z86E04/E08 and Z86C04/C08 do not support the instructions of LDE and LDEI). When the device is programmed for ROM Protect, the Low Noise feature will not automatically be enabled.

Please note that when using the device in a noisy environment, it is suggested that the voltages on the EPM and $\overline{CE}$ pins be clamped to V_{CC} through a diode to V_{CC} to prevent accidentally entering the OTP Mode. The V_{PP} requires both a diode and a 100 pF capacitor.

Auto Latch Disable. Auto Latch Disable option bit when programmed will globally disable all Auto Latches.

WDT Enable. The WDT Enable option bit, when programmed, will have the hardware enabled Permanent WDT enabled after exiting reset and can not be stopped in Halt or Stop Mode.

EPROM/Test Mode Disable. The EPROM/Test Mode Disable option bit, when programmed, will disable the EPROM Mode and the Factory Test Mode. Reading, verifying, and programming the Z8 will be disabled. To fully verify that this mode is disabled, the device must be power cycled.

User Modes. Table 7 shows the programming voltage of each mode.

Table 7. OTP Programming Table

Programming Modes	V_{PP}	EPM	$\overline{CE}$	$\overline{OE}$	$\overline{PGM}$	ADDR	DATA	V_{CC}*
EPROM READ	NU	V_H	V_{IL}	V_{IL}	V_{IH}	ADDR	Out	5.0V
PROGRAM	V_H	V_{IH}	V_{IL}	V_{IH}	V_{IL}	ADDR	In	6.4V
PROGRAM VERIFY	V_H	V_{IH}	V_{IL}	V_{IL}	V_{IH}	ADDR	Out	6.4V
EPROM PROTECT	V_H	V_H	V_H	V_{IH}	V_{IL}	NU	NU	6.4V
LOW NOISE SELECT	V_H	V_{IH}	V_H	V_{IH}	V_{IL}	NU	NU	6.4V
AUTO LATCH DISABLE	V_H	V_{IH}	V_H	V_{IL}	V_{IL}	NU	NU	6.4V
WDT ENABLE	V_H	V_{IL}	V_H	V_{IH}	V_{IL}	NU	NU	6.4V
EPROM/TEST MODE	V_H	V_{IL}	V_H	V_{IL}	V_{IL}	NU	NU	6.4V

Notes:

1. V_H =12.75V ± 0.25 V_{DC} .
2. V_{IH} = As per specific Z8 DC specification.
3. V_{IL} = As per specific Z8 DC specification.
4. X = Not used, but must be set to V_H or V_{IH} level.
5. NU = Not used, but must be set to either V_{IH} or V_{IL} level.
6. I_{PP} during programming = 40 mA maximum.
7. I_{CC} during programming, verify, or read = 40 mA maximum.
8. * V_{CC} has a tolerance of ±0.25V.

FUNCTIONAL DESCRIPTION (Continued)

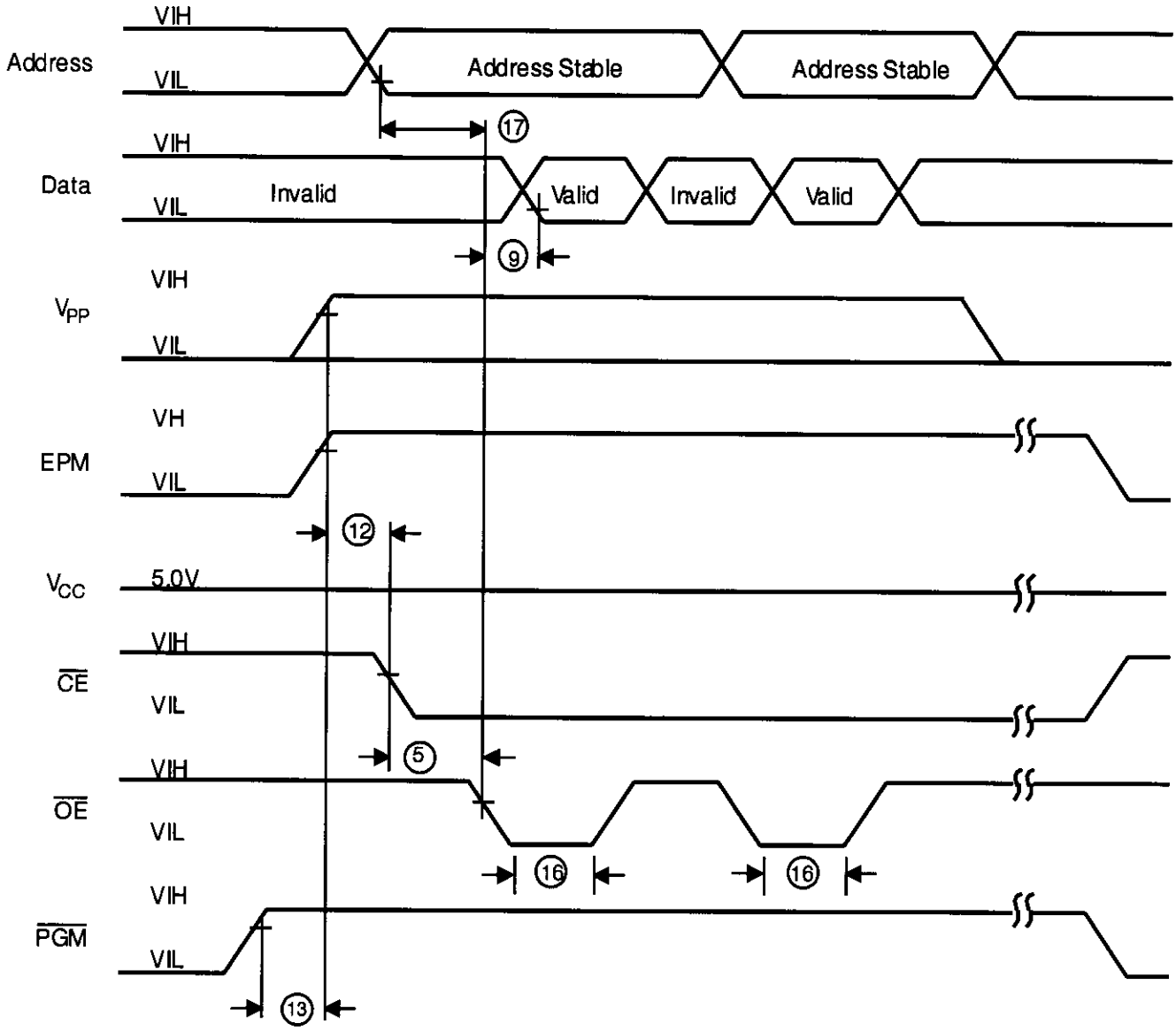


Figure 19. Z86E04/E08 Programming Waveform (EPROM Read)

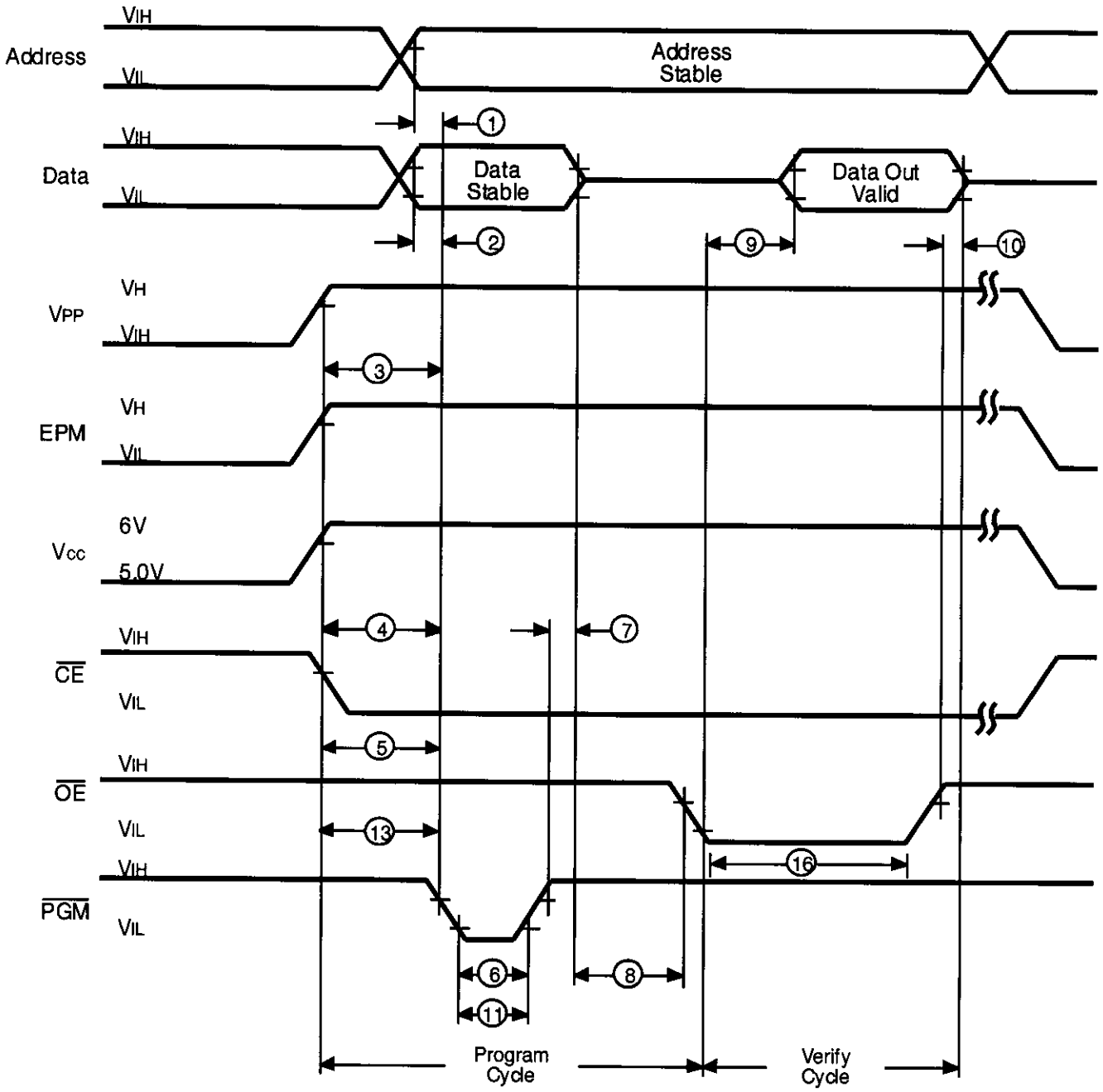


Figure 20. Z86E04/E08 Programming Waveform (Program and Verify)

FUNCTIONAL DESCRIPTION (Continued)

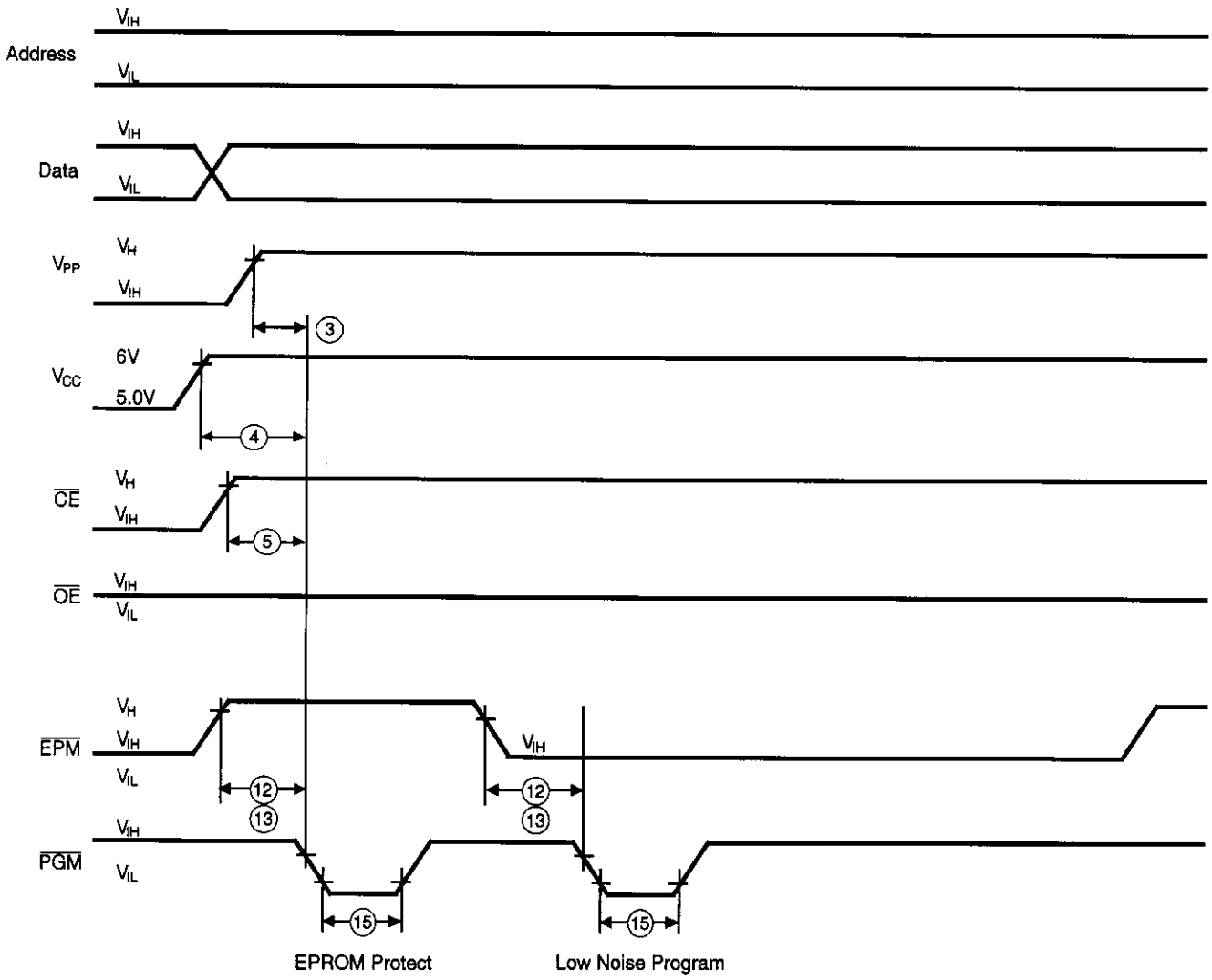


Figure 21. Z86E04/E08 Programming Options Waveform (EPROM Protect and Low Noise Program)

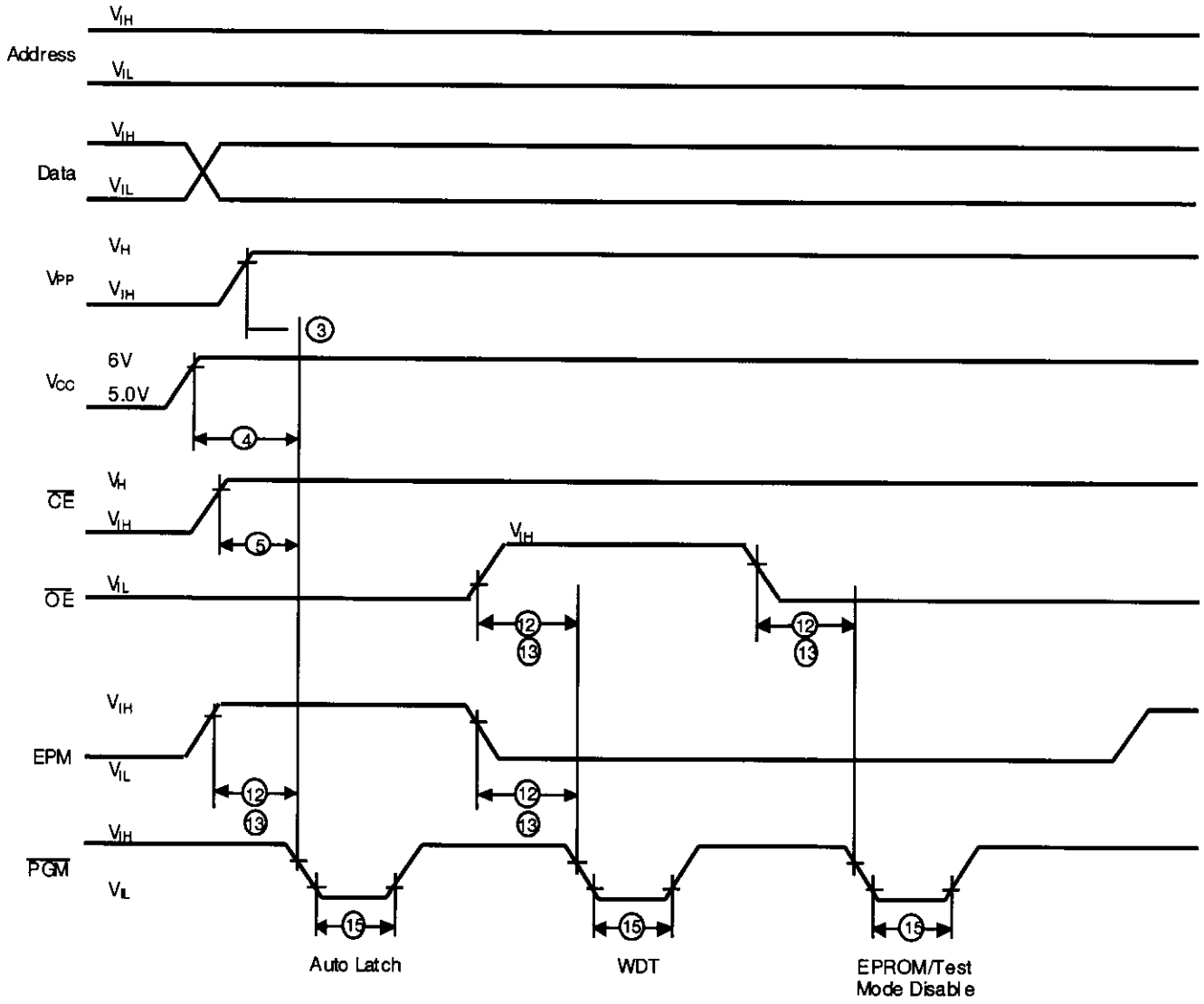


Figure 22. Z86E04/E08 Programming Options Waveform (Auto Latch Disable, Permanent WDT Enable and EPROM/Test Mode Disable)

Z8 CONTROL REGISTERS (Continued)

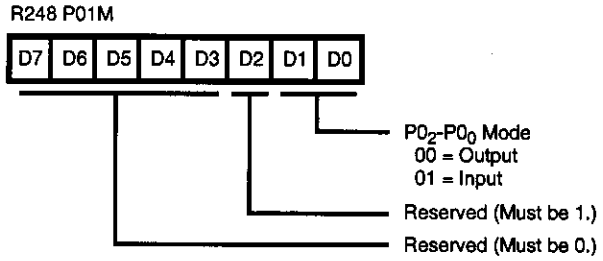


Figure 31. Port 0 and 1 Mode Register ($F8_H$: Write Only)

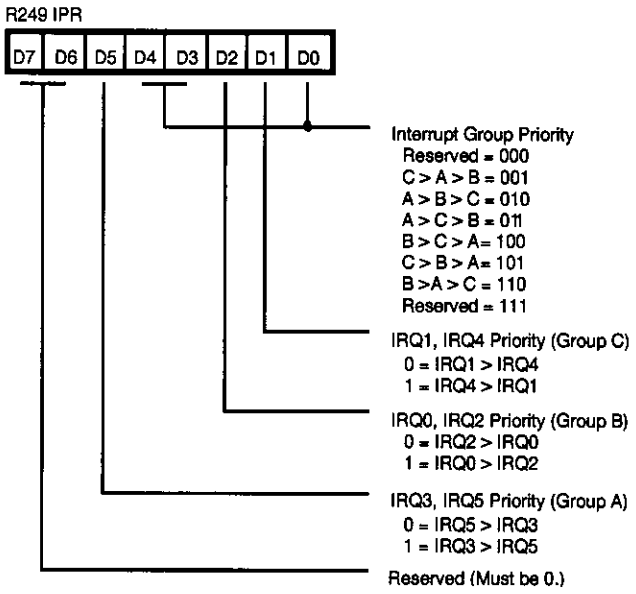


Figure 32. Interrupt Priority Register ($F9_H$: Write Only)

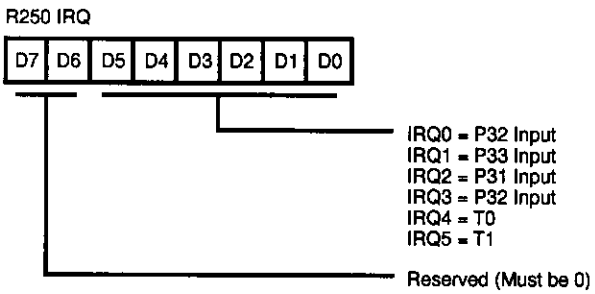


Figure 33. Interrupt Request Register (FA_H: Read/Write)

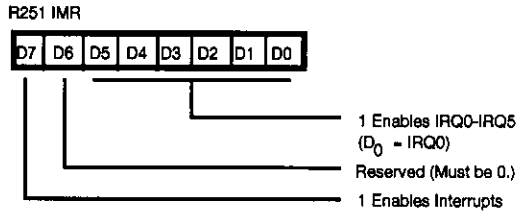


Figure 34. Interrupt Mask Register (FB_H: Read/Write)

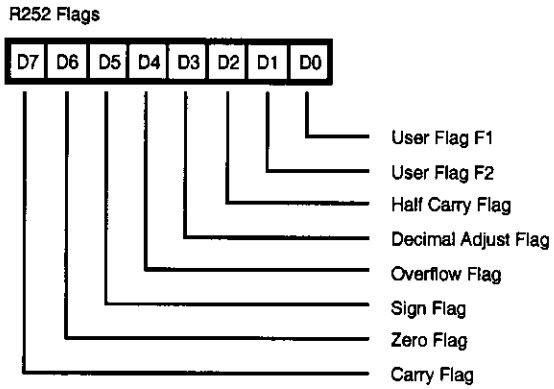


Figure 35. Flag Register (FC_H: Read/Write)

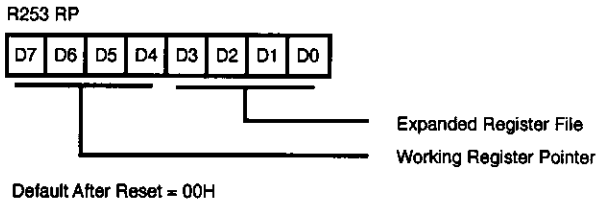


Figure 36. Register Pointer (FD_H: Read/Write)

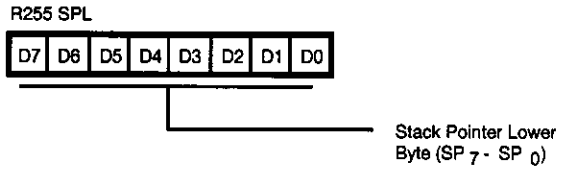


Figure 37. Stack Pointer (FF_H: Read/Write)